



SPECIFICATION

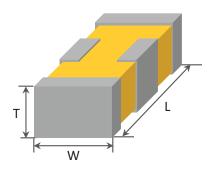
- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL05A435MR5NWNC
- Description : CAP, 4.3 µF, 4V, ±20%, X5R ,0402

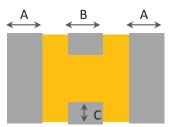
(Reference sheet)

A. Samsung Part Number

		<u>CL</u>	<u>05</u>	<u>A</u>	<u>435</u>	M	<u>R</u>	<u>5</u>	N	W	<u>N</u>	<u>C</u>
		1	2	3	4	5	6	1	8	9	10	(1)
1	Series	Samsung Mult	i-lavo	r Co	ramic	Cana	citor					
Ŭ		Samsung Multi-layer Ceramic Capacitor										
(2)	Size	0402 (inch c	ode)		L:	1.05	± 0.0	5	mm		VV:	0.65 ± 0.05 mm
3	Dielectric	X5R				8	Inner	· elec	trod	е		Ni
4	Capacitance	4.3 µF					Term	inati	on			Cu
5	Capacitance	±20 %					Plati	ng				Sn 100% (Pb Free)
	tolerance					9	Prod	uct				3-Terminal
6	Rated Voltage	4 V				10	Spec	ial				Reserved for future use
\bigcirc	Thickness	0.45 ±0.05	mm			1	Pack	agin	g			Cardboard Type, 7" reel

B. Structure and Dimensions





Samsung P/N	Dimension(mm)								
(Lead Free)	I	W	т	BW					
	L			A	В	С			
CL05A435MR5NWNC	1.05±0.05	0.65±0.05	0.45±0.05	0.17±0.10	0.35±0.10	0.15±0.10			

C. Samsung Reliability Test and Judgement condition

	Performance	Test condition			
Capacitance	Within specified tolerance	1kt±10% 0.5±0.1Vrms *A capacitor prior to measuring the capacitance is heat treated at 150℃+0/-10℃ for 1hour and maintained in			
Tan δ (DF)	0.125 max.	ambient air for 24±2 hours.			
Insulation	10,000Mohm or 50Mohm µF	Rated Voltage 60~120 sec.			
Resistance	Whichever is smaller				
Appearance	No abnormal exterior appearance	Visual inspection			
Withstanding	No dielectric breakdown or	250% of the rated voltage			
Voltage	mechanical breakdown				
Temperature	X5R				
Characteristics	(From -55℃ to 85℃, Capacitance chan	ge should be within ±15%)			
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.			
of Termination	terminal electrode				
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm) with 1.0mm/sec.			
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder			
-	is to be soldered newly	245±5℃, 3±0.3sec.			
		(preheating : 80~120 ℃ for 10~30sec.)			
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5℃, 10±1sec.			
Soldering heat	Tan δ, IR : initial spec.				
Vibration Test	Capacitance change : within $\pm 5\%$ Tan δ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours × 3 direction (x, y, z)			
Moisture	Capacitance change : within ±12.5%	With rated voltage			
Resistance	Tan δ : 0.25 max	40±2℃, 90~95%RH, 500+12/-0hrs			
	IR : 500Mohm or 8.8 Mohm · µF Whichever is smaller				
High Temperature	Capacitance change : within ±12.5%	With 100% of the rated voltage			
Resistance	Tan δ : 0.25 max	Max. operating temperature			
	IR : 1,000Mohm or 17.7Mohm · μF				
	Whichever is smaller	1000+48/-0hrs			
Temperature	Capacitance change : within ±10%	1 cycle condition			
Cycling	Tan δ, IR : initial spec.	Min. operating temperature \rightarrow 25 °C			
		\rightarrow Max. operating temperature \rightarrow 25 °C			
		5 cycle test			

* The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)

Product specifications included in the specifications are effective as of March 1, 2013. Please be advised that they are standard product specifications for reference only. We may change, modify or discontinue the product specifications without notice at any time. So, you need to approve the product specifications before placing an order. Should you have any question regarding the product specifications, please contact our sales personnel or application engineers.